

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3130974

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YUANKUN HOU	11/24/2014
KUANCHIEH YU	11/24/2014
YU HUA	11/24/2014
YUELIN ZHAO	11/24/2014
RECEIVING PARTY DATA	
Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION
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Internal Address:	PUDONG NEW AREA
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State/Country:	CHINA
Postal Code:	201203
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14559197
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SIGNATURE:	/Hin Au/
DATE SIGNED:	12/03/2014
Total Attachments: 2	

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CLIENT REFERENCE NO.: 2013-01320-SH-US
ATTORNEY DOCKET NO.: PCAS00005 US

ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we

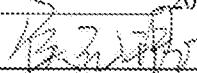
Yuankun HOU	of	18 Zhangjiang Road Pudong New Area Shanghai, P.R.C. 201203
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Yu HUA	of	18 Zhangjiang Road Pudong New Area Shanghai, P.R.C. 201203
Yuelin ZHAO		18 Zhangjiang Road Pudong New Area Shanghai, P.R.C. 201203

hereby sell, assign and transfer to **Semiconductor Manufacturing International (Shanghai) Corporation**, having a place of business at 18 Zhangjiang Road, Pudong New Area, Shanghai, P.R.C. 201203, its successors and assigns, the entire right, title and interest throughout the world in our invention in

A SEALING STRUCTURE FOR A BONDED WAFER AND METHOD OF FORMING THE SEALING STRUCTURE

for which we have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisionals, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from me; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request that the United States Patent and Trademark Office issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 24 day of November, 2014.



 Yuankun HOU

CLIENT REFERENCE NO.: 2013-01320-SH-US
ATTORNEY DOCKET NO.: PCAS00005 US

WITNESSED:

Signature [Handwritten Signature]

Date 2014-11-25

Type or print name of witness

Executed this 24 day of November, 2014.

[Handwritten Signature]
Kuanchieh YU

WITNESSED:

Signature [Handwritten Signature]

Date 2014-11-25

Type or print name of witness

Executed this 24 day of November, 2014.

[Handwritten Signature]
Yi HUA

WITNESSED:

Signature [Handwritten Signature]

Date 2014.11.25

Type or print name of witness

Executed this 24 day of November, 2014.

[Handwritten Signature]
Yuelin ZHAO

WITNESSED:

Signature [Handwritten Signature]

Date 2014.11.25

Type or print name of witness